FMXS-4202S

Fast Recovery Diode

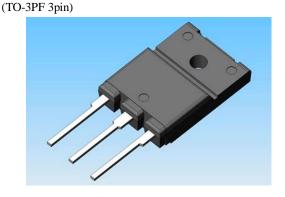
June, 2011

General Description

FRD that has excellent high speed performance is incorporated into the TO-3PF at high current package. It achieved a balance between high speed at high temperature operates and low-VF.

Applications

- A DC-DC converters.
- A high current secondary rectifier.
- A high frequencies rectifier circuit, etc.

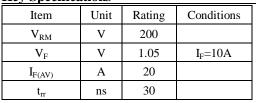


Key Specifications

Package

Features

- An ultrafast recovery diode.
- A balance low-VF and high speed performance at high temperature.
- A great radiation performance due to high-current package.
- A great isolation performance due to full mold package.



Typical Characteristics VF-IF Characteristics VR-IR Characteristics 100 1.0E-02 150°C 10 1.0E-03 100°C 1 1.0E-04 60°C З Ш R 0.1 150°C 1.0E-05 100°C 25°C 60°C 0.01 1.0E-06 25°C 0.001 1.0E-07 0.0 0.5 1.0 1.5 2.0 n 50 100 150 200 VF (V) VR(V)

VF-IF&VR-IR show ratings per one chip.

The information included herein is believed to be accurate and reliable. However, SANKEN ELECTRIC CO., LTD assumes no responsibility for its use ; nor for any infringements of patents or other rights of third parties that may result from its use.

FMXS-4202S

June, 2011

Fast Recovery Diode

* Absolute maximum ratings

No.	Item	Symbol	Unit	Rating	Conditions
1	Transient Peak Reverse Voltage	Vrsm	V	200	
2	Peak Reverse Voltage	Vrm	V	200	
3	Average Forward Current	I _{F(AV)}	А	20	
4	Peak Surge Forward Current	I _{FSM}	А	150	10msec. Half sinewave, one shot
5	I ² t Limiting Value	I²t	A ² s	112.5	$1msec \ \le \ t \ \le \ 10msec$
6	Junction Temperature	T_j	°C	-40 ~ +150	
7	Storage Temperature	T _{stg}	°C	-40 ~ +150	

No.1,2,4&5 show ratings per one chip.

★ Electrical characteristics (Ta=25°C, unless otherwise specified)

No.	Item	Symbol	Unit	Value	Conditions
1	Forward Voltage Drop	V_{F}	V	1.05 max.	I _F =10A
2	Reverse Leakage Current	I_R	uA	50 max.	V _R =V _{RM}
3	Reverse Leakage Current Under High Temperature	$H \cdot I_R$	mA	30 max.	$V_R = V_{RM}, T_j = 150^{\circ}C$
4	Reverse Recovery Time	trr1	ns	30 max.	$I_{F}=I_{RP}=500$ mA, $T_{j}=25^{\circ}$ C, 90% Recovery point
		trr2	ns	25 max.	$I_F=500mA, I_{RP}=1A, T_j=25^{\circ}C, 75\%$ Recovery point
5	Thermal Resistance	$R_{th(j-l)}$	°C /W	2.0 max.	Between Junction and case

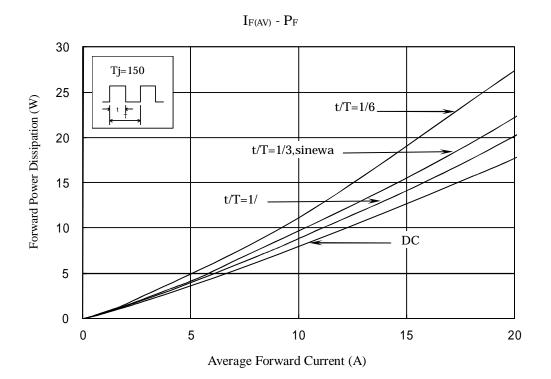
No.1,2,3&4 show characteristics per one chip.

FMXS-4202S

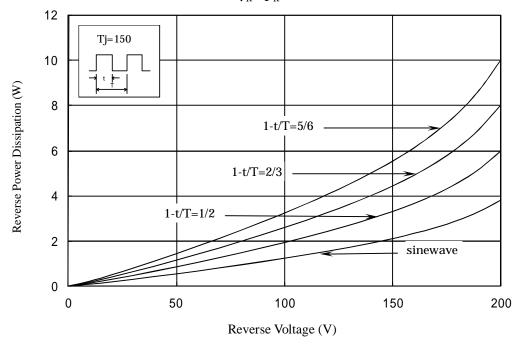
Fast Recovery Diode

June, 2011

* Characteristics



VR - PR



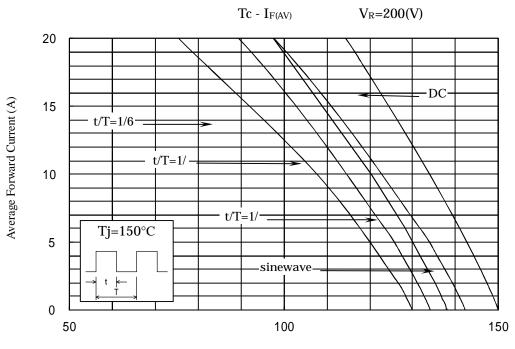
The information included herein is believed to be accurate and reliable. However, SANKEN ELECTRIC CO., LTD assumes no responsibility for its use ; nor for any infringements of patents or other rights of third parties that may result from its use.

FMXS-4202S

June, 2011

Fast Recovery Diode

***** Derating



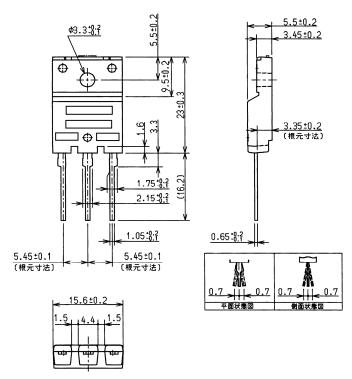
Case Temperature ()

The information included herein is believed to be accurate and reliable. However, SANKEN ELECTRIC CO., LTD assumes no responsibility for its use; nor for any infringements of patents or other rights of third parties that may result from its use.

FMXS-4202S

Fast Recovery Diode

★ Package information (**mm**)





The information included herein is believed to be accurate and reliable. However, SANKEN ELECTRIC CO., LTD assumes no responsibility for its use; nor for any infringements of patents or other rights of third parties that may result from its use.

June, 2011